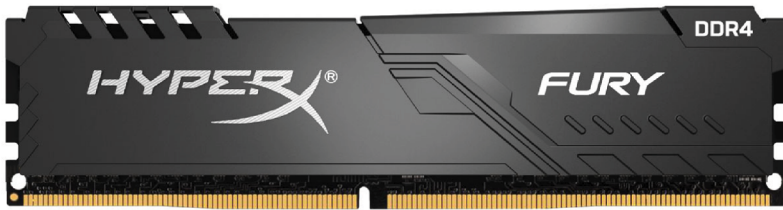


Memory Module Specifications

HX432C16FB3/16

16GB 2G x 64-Bit

DDR4-3200 CL16 288-Pin DIMM



SPECIFICATIONS

CL(IDD)	17 cycles
Row Cycle Time (tRCmin)	45.75ns(min.)
Refresh to Active/Refresh Command Time (tRFCmin)	350ns(min.)
Row Active Time (tRASmin)	32ns(min.)
UL Rating	94 V - 0
Operating Temperature	0° C to +85° C
Storage Temperature	-55° C to +100° C

DESCRIPTION

HyperX HX432C16FB3/16 is a 2G x 64-bit (16GB) DDR4-3200 CL16 SDRAM (Synchronous DRAM) 1Rx8, memory module, based on sixteen 1G x 8-bit FBGA components per module. Each module kit supports Intel® Extreme Memory Profiles (Intel® XMP) 2.0. Each module has been tested to run at DDR4-3200 at a low latency timing of 16-18-18 at 1.35V. The SPDs are programmed to JEDEC standard latency DDR4-2400 timing of 17-17-17 at 1.2V. Each 288-pin DIMM uses gold contact fingers. The JEDEC standard electrical and mechanical specifications are as follows:

FEATURES

- Power Supply: VDD = 1.2V Typical
- VDDQ = 1.2V Typical
- VPP = 2.5V Typical
- VDDSPD = 2.2V to 3.6V
- On-Die termination (ODT)
- 16 internal banks; 4 groups of 4 banks each
- Bi-Directional Differential Data Strobe
- 8 bit pre-fetch
- Burst Length (BL) switch on-the-fly BL8 or BC4(Burst Chop)
- Height 1.3425" (34.1mm), w/heatsink

FACTORY TIMING PARAMETERS

- Default (JEDEC): DDR4-2400 CL17-17-17 @1.2V
- XMP Profile #1: DDR4-3200 CL16-18-18 @1.35V
- XMP Profile #2: DDR4-3000 CL15-17-17 @1.35V

Continued >>

